

# PGB Series 0805 Surface Mount ESD Suppressor

### Product Overview

PulseGuard ESD Suppressors help protect sensitive electronic equipment against electrostatic discharge (ESD). They supplement the on-chip protection of integrated circuitry and are best suited for low-voltage, high-speed applications where low capacitance is important. Data ports utilizing such high-speed protocols as USB 2.0, IEEE1394 and InfiniBand<sup>SM</sup> can benefit from this new technology. PulseGuard suppressors use polymer composite materials to suppress fast-rising ESD transients (as specified in IEC 61000-4-2 and MIL-STD-883E).

### Features

- Ultra-low capacitance
- Low leakage current
- Fast response time
- 4-lines of protection
- Bi-directional
- Withstands multiple ESD strikes
- Based on industry standard 2012 package
- Compatible with pick-and-place processes
- Available in 1,000 and 5,000 piece reels (EIA-RS481)

### Typical Applications

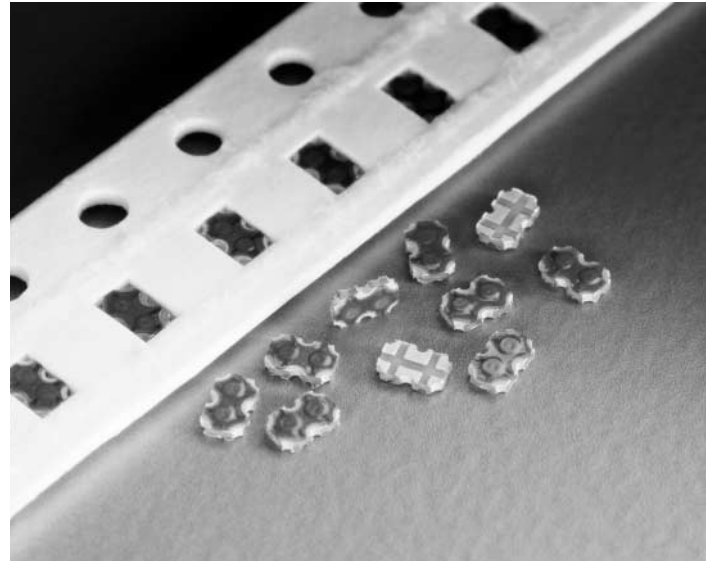
- Servers
- Laptop/Desktop Computers
- Network Hardware
- Computer Peripherals
- Digital Cameras
- External Storage

### Electrical Characteristics

Trigger Voltage <sup>1</sup> . . . . .	1,000 V, typical
Clamping Voltage <sup>1</sup> . . . . .	150V, typical
Rated Voltage . . . . .	24VDC, max
Capacitance <sup>2</sup> . . . . .	0.055 pF
Response Time <sup>1</sup> . . . . .	< 1ns
Leakage Current . . . . .	< 1nA
ESD Pulse Withstand <sup>1</sup> . . . . .	1,000 pulses, minimum

#### NOTES:

1. 8 kV direct discharge method, per IEC 61000-4-2.
2. Measured at 1 MHz.
3. Measured at 6 VDC. Testing at fast ESD pulse rates (1-20Hz) may cause a change in leakage current performance (6µA, max).



### Physical Specifications

#### Materials:

Body: Glass Epoxy

Terminations: Tin-Lead

#### Soldering Parameters:

Wave solder -- 260°C, 10 seconds maximum

Reflow solder -- 260°C, 30 seconds maximum

#### Operating Temperature Range:

-65°C to 125°C

### Ordering Information

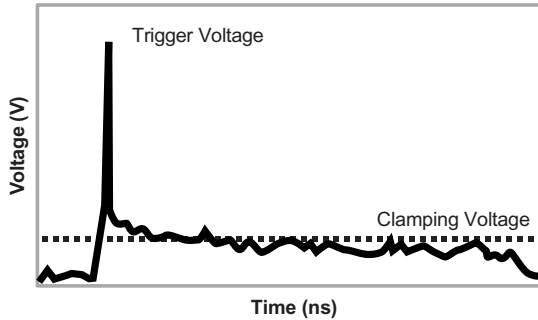
CATALOG NUMBER	PIECES PER REEL
PGB0040805MR	1,000
PGB0040805NR	5,000

### Design Consideration

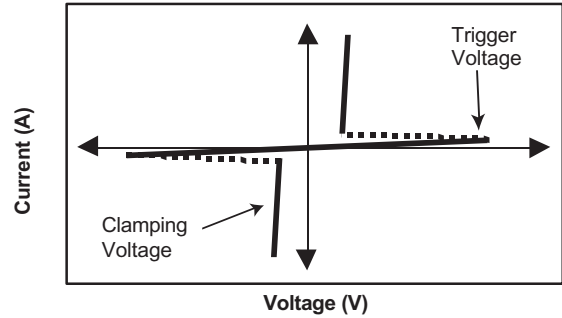
Because of the fast rise-time of the ESD transient, placement of PulseGuard suppressors is a key design consideration. To achieve optimal ESD suppression, the devices should be placed on the circuit board as close to the source of the ESD transient as possible. Install PulseGuard suppressors directly behind the connector so that they are the first board-level circuit component encountered by the ESD transient. They are connected from signal/data line to ground.

### PGB Series 0805 Surface Mount ESD Suppressor

**Generalized PulseGuard Suppressor Response to ESD**  
(Positive and Negative Polarity ESD Pulses)



**Generalized I-V Curve**  
(Positive and Negative Polarity ESD Pulses)



#### Definitions

**Trigger Voltage:** The measured peak voltage across the ESD suppressor before it transitions from high to low resistance. It is manifested as a “spike” before the clamping voltage is achieved. This voltage is typically well below the damage threshold of on-chip IC protection.

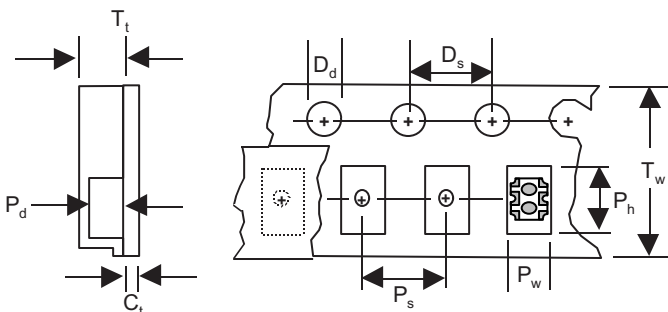
**Clamping Voltage:** The voltage level to which the ESD impulse voltage is reduced. This is the voltage that the suppressor holds at, until the ESD transient energy is dissipated.

**ESD Impulse Voltage:** Also known as the ESD Threat Voltage. This is the voltage that is “zapped” into the circuit. Voltages generated by people can exceed 15 kV. The IEC 61000-4-2 defines four levels of impulse voltage for testing purposes:

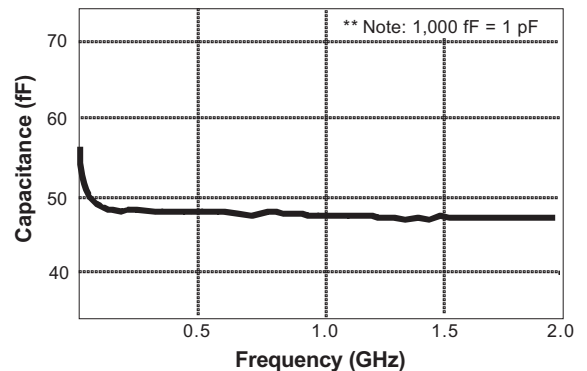
SEVERITY LEVEL	AIR DISCHARGE	DIRECT DISCHARGE
1	2 kV	2 kV
2	4 kV	4 kV
3	8 kV	6 kV
4	15 kV	8 kV

#### Carrier Tape Specifications

Parts are delivered on 7" (178mm) reel, paper carrier tape



**Capacitance vs. Frequency**

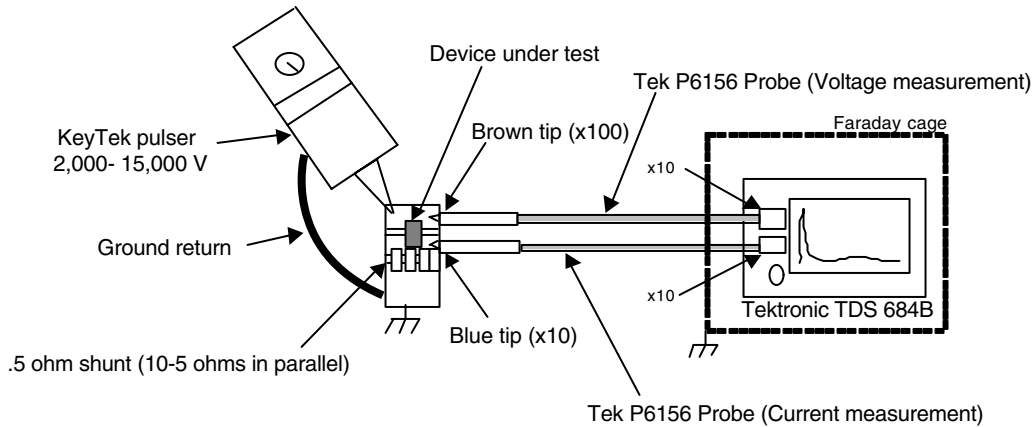


DESCRIPTION	MEASUREMENT (MM)
C <sub>t</sub> - Cover tape thickness	0.06
D <sub>d</sub> - Drive hole diameter	1.50
D <sub>s</sub> - Drive hole spacing	4.00
P <sub>d</sub> - Pocket depth	0.58
P <sub>h</sub> - Pocket height	2.21
P <sub>s</sub> - Pocket spacing	4.00
P <sub>w</sub> - Pocket width	1.45
T <sub>t</sub> - Carrier tape thickness	0.65
T <sub>w</sub> - Carrier tape width	8.00

4  
PULSEGUARD®  
SUPPRESSORS

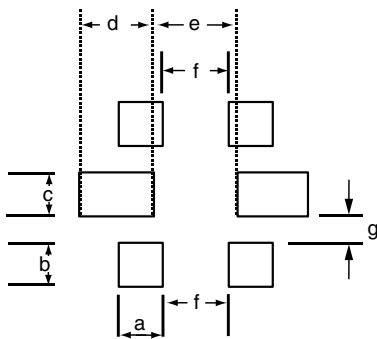
# PGB Series 0805 Surface Mount ESD Suppressor

Test Set-up for IEC 61000-4-2 Waveform, 2kV-15kV

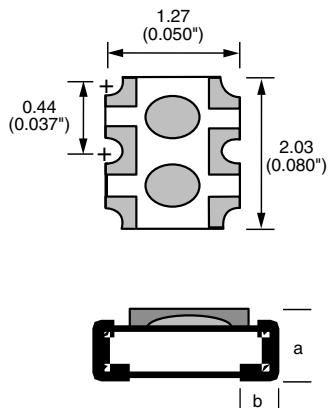


### Reference Schematics:

#### Recommended Pad Layout:

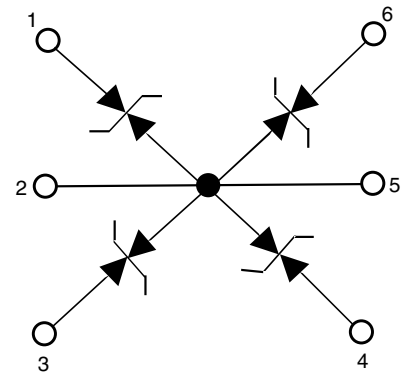


#### Device Dimensions:



\* Dimension "a" is: 0.456 (.016")  
 \* Dimension "b" is: 0.660 (.026")

#### Equivalent Circuit:



SOLDER METHOD	A		B		C		D		E		F		G	
	INCH	MM	INCH	MM	INCH	MM	INCH	MM	INCH	MM	INCH	MM	INCH	MM
Wave Solder	0.029	0.74	0.029	0.74	0.028	0.71	0.050	1.27	0.025	0.635	0.020	0.51	0.011	0.279
Reflow Solder	0.029	0.74	0.029	0.74	0.028	0.71	0.050	1.27	0.025	0.635	0.020	0.51	0.011	0.279

**Note:** Pins 2 and 5 (Common) are typically connected to chassis ground. However since PulseGuard suppressors are electrically bi-directional, the system voltage bus can also be used as the ESD "dump".